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(54) **Title:** SYSTEMS AND METHODS FOR CARRYING SINGULATED DEVICE PACKAGES

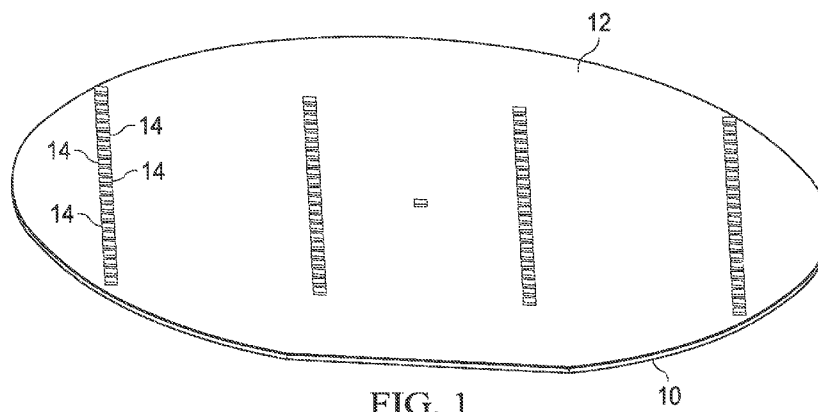


FIG. 1

(57) **Abstract:** In accordance with embodiments of the present disclosure, a method may include providing a substrate (10) adapted for use in wafer processing equipment, wherein the substrate includes an adhesive (12) applied thereto. The method may also include reconstituting a plurality of device packages (14) onto the substrate. In accordance with these and other embodiments of the present disclosure, an apparatus may include a substrate (10) adapted for use in wafer processing equipment, an adhesive (12) applied to the substrate, and a plurality of device packages (14) reconstituted onto the substrate. The device packages (14) are subjected to testing when reconstituted on the substrate (10).

